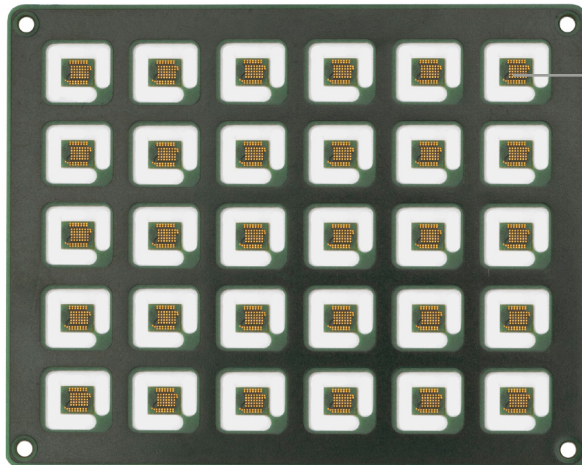
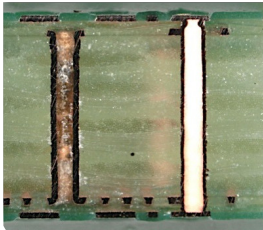
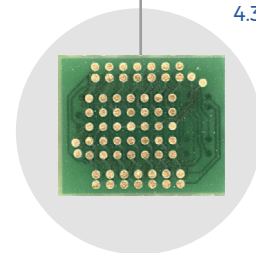


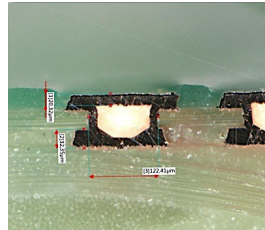
HDI PCB



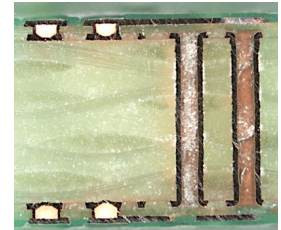
PCB DIMENSION
4.3x3.5mm



Buried holes $\pm 0,15\text{mm}$ and vias
resin filled and CU capped



Blind vias $\pm 0,1\text{mm}$ with resin
filled and CU capped



Buried holes $\pm 0,15\text{mm}$ and blind vias $\pm 0,12\text{mm}$ with resin filled and CU capped

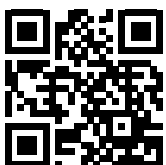
OVERVIEW

HDI PCBs are a technologically advanced solution to reduce size, improve performance, and increase the reliability of modern electronic devices. The use of microvias, multilayer stack-ups, and innovative materials makes these PCBs essential for high-density and high-speed applications.

TECHNICAL DATA

| | |
|---------------------------|------------------------|
| TECHNOLOGY | HDI PCBs |
| TYPE: | 4 layers |
| BASE MATERIAL: | HTg |
| THICKNESS: | 1mm |
| PCB DIMENSION: | 4.3x3.5mm |
| MIN. FINISH HOLES: | 0,12mm |
| FINISHING: | ENIG |
| PLATING: | 2 STEPS OF PLATING |
| DRILL: | 4 STEPS OF DRILLING |

| | |
|-------------------|---|
| HOLES | BURRIED VIAS RESIN FILLED AND Cu CAPPED (IPC4761 type VII) VIAS RESIN FILLED AND Cu CAPPED (IPC4761 type VII) |
| TECHNOLOGY | 2 STEPS OF COPPER REDUCTION ANNULAR RING 25um MIN. COPPER TO COPPER DISTANCE |



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